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Day : Monday
Date: 3/19/2007
Time: 15:42:16

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[Appln Info](#)[Contents](#)[Petition Info](#)[Atty/Agent Info](#)[Continuity/Reexam](#)[Foreign Data](#)[Invento](#)Search Another: Application# or Patent# PCT / / or PG PUBS # Attorney Docket # Bar Code #

To go back use Back button on your browser toolbar.

[Back to PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)

US 20070057378 A1	20070315	Electronic device and manufacturing method therefor	257/777		Arai; Kazuhisa et al.
US 20070029684 A1	20070208	Wafer dividing method		257/E21.237; 438/432	Arai; Kazuhisa et al.
US 20060288826 A1	20061228	Method of preparing terminal board	82/1.11	257/E23.069	Arai; Kazuhisa et al.
US 20060073705 A1	20060406	Method for dividing semiconductor wafer along streets	438/706	257/E21.218; 257/E21.599	Arai; Kazuhisa et al.
US 20050233548 A1	20051020	Method for fabricating semiconductor wafer	438/459	438/457; 438/691; 438/692	Arai, Kazuhisa
US 20050221584 A1	20051006	Wafer processing method	438/458	257/E21.224; 257/E21.237; 438/17; 438/459	Arai, Kazuhisa
US 20050106840 A1	20050519	Method of manufacturing semiconductor wafer	438/459	257/E21.237	Arai, Kazuhisa
US 20050103635 A1	20050519	Method of producing micro component	205/74	205/112; 205/118	Arai, Kazuhisa et al.
US 20040241961 A1	20041202	Method for processing soi substrate	438/459	257/E21.219; 257/E21.569; 438/403	Takahashi, Toshiaki et al.
US 20040209554 A1	20041021	Polishing material and method of polishing therewith	451/36	451/41	Tsumagari, Akio et al.
US 20040208718 A1	20041021	Machine for processing electrodes formed on a plate-like workpiece	409/139	257/E21.508; 409/166; 409/167	Arai, Kazuhisa et al.

US 20040206800 A1	20041021	Flip chip bonder	228/6.2	228/49.1; 257/E21.511	Arai, Kazuhisa et al.
US 20040203187 A1	20041014	Method for manufacturing semiconductor wafer	438/106	257/E21.508; 257/E23.021	Sekiya, Kazuma et al.
US 20040124413 A1	20040701	Wafer support plate	257/48	211/41.1; 211/41.18; 269/902	Arai, Kazuhisa et al.
US 20040089958 A1	20040513	Conductor wafer and substrate	257/797	257/E23.179	Arai, Kazuhisa
US 20030181150 A1	20030925	Semiconductor wafer assembly and machining apparatus having chuck tables for holding the same	451/285	451/388; 451/41	Arai, Kazuhisa et al.
US 20030027501 A1	20030206	Method of grinding rear side of semiconductor wafer	451/41		Arai, Kazuhisa
US 20030013380 A1	20030116	Semiconductor wafer dividing method	451/6	257/E21.238; 257/E21.599	Arai, Kazuhisa et al.
US 20020045348 A1	20020418	Semiconductor wafer treating method and device for removing deposit on a semiconductor wafer	438/690	257/E21.237; 438/906	Arai, Kazuhisa
US 20020025656 A1	20020228	Semiconductor chip pick-up method	438/463	257/E21.599	Arai, Kazuhisa et al.
US 20020023340 A1	20020228	Method of separating a plate-like workpiece adsorption-	29/825	29/426.1	Arai, Kazuhisa et al.

		held on an elastic adsorption pad			
US 20020004359 A1	20020110	Semiconductor wafer grinding Method	451/41	451/54	Arai, Kazuhisa
US 20010049256 A1	20011206	Semiconductor wafer assembly and machining apparatus having chuck tables for holding the same	451/289		Arai, Kazuhisa et al.
US 20010029938 A1	20011018	Semiconductor wafer cutting machine	125/13.01		Arai, Kazuhisa et al.
US 7183178 B2	20070227	Method of manufacturing semiconductor wafer	438/459	257/E21.237; 257/E21.484; 257/E21.567; 438/458; 438/464	Arai; Kazuhisa
US 6927416 B2	20050809	Wafer support plate	257/48	257/627	Arai; Kazuhisa et al.
US 6759274 B2	20040706	Semiconductor chip pick-up method	438/114	257/E21.599; 414/941; 438/118	Arai; Kazuhisa et al.
US 6702652 B2	20040309	Method of grinding rear side of semiconductor wafer	451/41	156/345.12; 438/692; 451/63	Arai; Kazuhisa
US 6676491 B2	20040113	Semiconductor wafer dividing method	451/57	125/13.01; 257/E21.238; 257/E21.599; 438/460	Arai; Kazuhisa et al.
US 6594890 B2	20030722	Method of separating a plate-like workpiece held by adhesion on an elastic adsorption pad	29/830	29/426.1; 29/825; 438/464	Arai; Kazuhisa et al.

US 6528864 B1	20030304	Semiconductor wafer having regular or irregular chip pattern and dicing method for the same	257/620	257/622; 257/E21.238; 257/E21.599	Arai; Kazuhisa
US 6527627 B2	20030304	Semiconductor wafer grinding method	451/41	451/57	Arai; Kazuhisa
US 6500047 B2	20021231	Semiconductor wafer cutting machine	451/14	125/13.01; 451/11	Arai; Kazuhisa et al.
US 6358132 B1	20020319	Apparatus for grinding spherical objects	451/296	451/300; 451/302	Arai; Kazuhisa et al.